

ABSTRACT

WIRE BONDING APPARATUS COMPRISING ROTARY POSITIONING STAGE

A wire bonding apparatus, comprising a bonding tool mounted on a bondhead body which is in turn mounted on a positioning table, is provided for bonding electronic devices. The positioning table has first and second motors coupled to it that are operative to drive the bondhead body to positions along respective first and second orthogonal axes. The bondhead body is connected to the positioning table through a pivot such that the bondhead body is rotatable relative to the positioning table about a third axis which is substantially orthogonal to the first and second axes. Further, a third motor drives the bondhead body to rotate about the third axis.

(FIG. 2)